

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please cancel claims 89-94 and 99, amend claims 100, 103-105, and 107, and add new claims 111-112 as follows:

Listing of Claims:

1-99. (Cancelled)

100. (Currently Amended) A method for removably attaching a planarizing medium to a platen of a planarizing machine, comprising:

embedding ~~distributing~~ a plurality of conductive particles in the planarizing medium; and

applying a signal to the platen that produces an electromagnetic attractive force between the platen and the conductive particles in the planarizing medium.

101. (Previously Presented) The method of claim 100, further comprising positioning the platen adjacent to the planarizing medium.

102. (Previously Presented) The method of claim 100 wherein the platen includes a conductive plate positioned within the platen, and applying a signal includes applying a signal to the conductive plate positioned within the platen.

103. (Currently Amended) The method of claim 100 wherein embedding ~~distributing~~ a plurality of conductive particles further comprises embedding ~~distributing~~ the plurality of conductive particles uniformly in the planarizing medium.

104. (Currently Amended) The method of claim 101 wherein embedding ~~distributing~~ a plurality of conductive particles further comprises concentrating the plurality of conductive particles in a portion of the planarizing medium adjacent to the platen.

105. (Currently Amended) The method of claim 100 wherein embedding ~~distributing~~ a plurality of conductive particles further comprises embedding ~~distributing~~ a plurality of particles in the planarizing medium that are comprised of a ferrous material.

106. (Previously Presented) The method of claim 100, wherein applying a signal includes applying a current to the platen.

107. (Currently Amended) A method for releasably attaching a planarizing medium having a plurality of ~~internally distributed~~ embedded conductive particles to a platen of a planarization machine, comprising:

positioning the planarization medium adjacent to the platen; and

coupling a signal to the platen to produce an electromagnetic attractive force between the conductive particles and the platen.

108. (Previously Presented) The method of claim 107, wherein the planarizing medium includes an attachment surface having a concentration of conductive particles located proximate to the attachment surface, and positioning the planarizing medium is further comprised of positioning the attachment surface on the platen.

109. (Previously Presented) The method of claim 107, wherein the platen includes a conductive member positioned within the platen, and coupling a signal to the platen further comprises coupling a signal to the conductive member.

110. (Previously Presented) The method of claim 107, wherein coupling a signal includes coupling a current to the platen.

111. (New) The method of claim 107, wherein the plurality of embedded conductive particles are uniformly distributed in the planarizing medium.

112. (New) The method of claim 107, wherein the plurality of embedded conductive particles are concentrated in a portion of the planarizing medium adjacent the platen.